

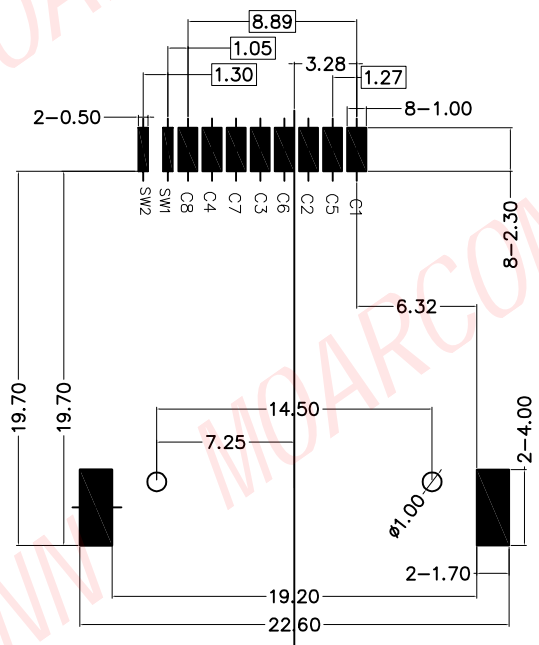
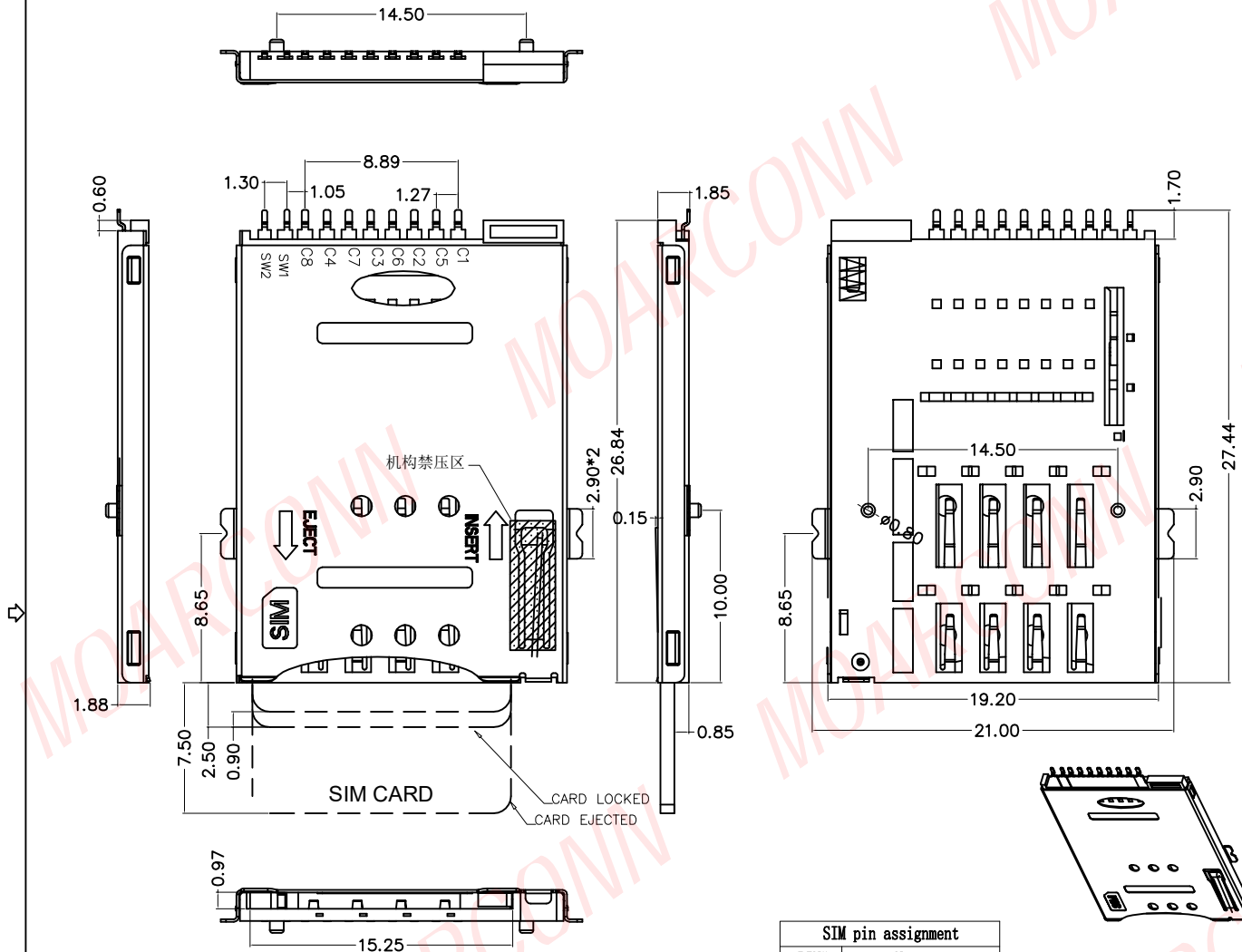
All materials, plating and process meet HF requirements.

Specification

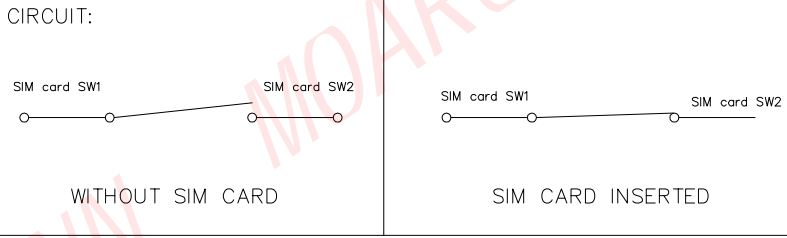
MATERIAL:
 Insulator: High Temperature Thermoplastic,
 UL 94V-0, COLOR:BLACK LCP
 Contact: Copper Alloy

PLATING:
 Contact: Plated 30μ" Ni Overall
 Plated Au Selective Contact Area
 Shell: Plated 30μ" Ni Overall, Pad G/P Au

Electrical:
 Current Rating :0.5Amps
 Voltage Rating :5V AC/DC
 Ambient Temperature Range :-20° C~+60° C
 Storage Temperature Range :-40° C~+70° C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩmax.
 Insulation Resistance:1000MΩmin./500VDC
 Mating Cycles:5,000 Insertions



RECOMMENDED PCB LAYOUT



SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

<p>MOARCONN MORE CONNECTIONS SMART FUTURE</p>	<p>DONG GUAN MOARCONN ELECTRONIC Co., Ltd.</p>		
	<p>DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE</p>	<p>PRODUCT NAME : SIM CARD CONN. PUSH TYPE 8PIN WITH SWITCH</p>	<p>DRAWING: Seven</p>
<p>DIMENSION TOLERANCE</p> <p>X.X: ± 0.35 X.XX: ± 0.15 X.XXX: ± 0.10 ANGULAR: ± 1°</p>	<p>PRODUCT NO. : SM185-T1250-02-W</p>	<p>CHECK:</p>	<p>DATE:</p>
<p>DRAWING NO. : D-SM185-T1250-02-W</p>	<p>APPROVED:</p>	<p>DATE:</p>	<p>DATE:</p>
<p>SCALE: 1:1</p>	<p>DWG ID: C D</p>	<p>REV.: A</p>	<p>PAGE: 1 OF 4</p>

A	---	NEW RELEASE	Seven	2021.09.06
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				